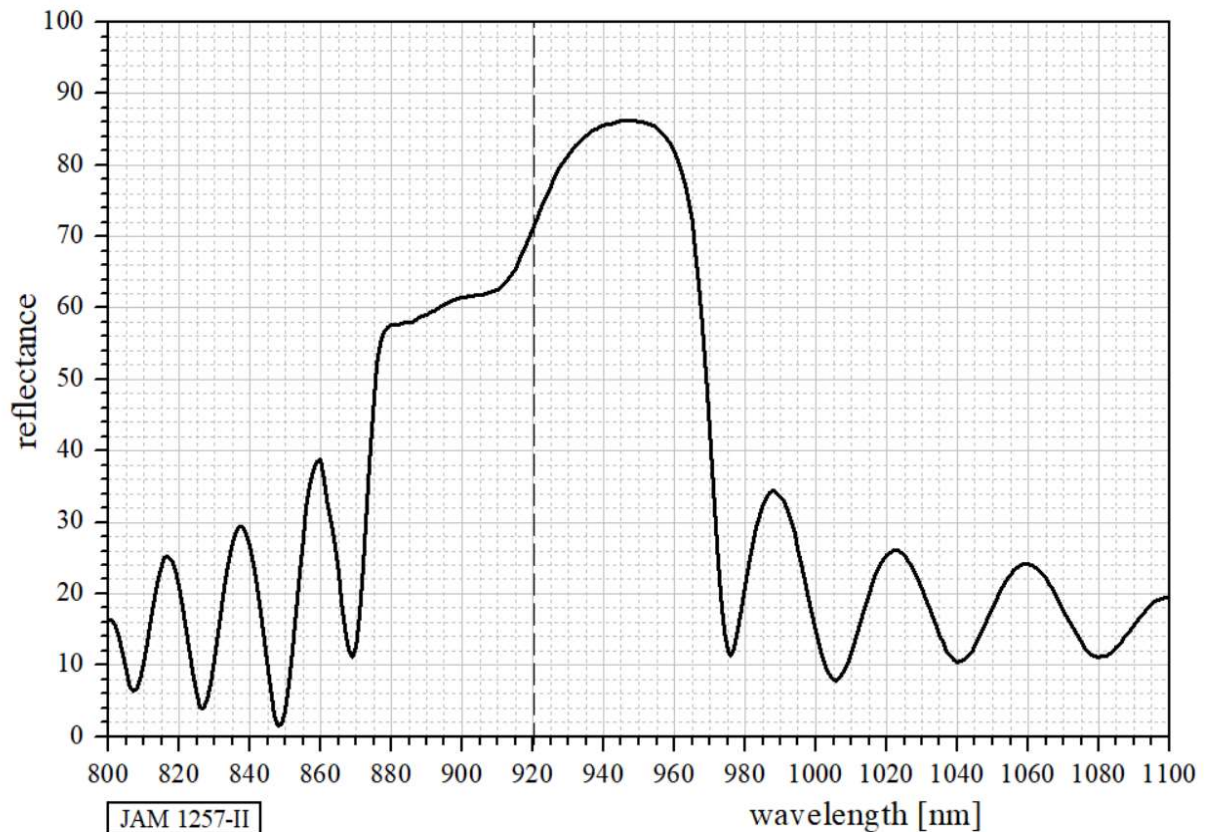
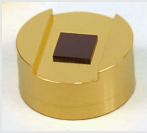
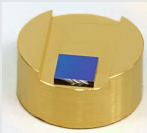


**SAM™ Data Sheet SAM-920-30-0.5ps-30-x,  $\lambda = 920$  nm**

	Minimum	Typical Value	Maximum
Operational wavelength $\lambda$		920 nm	
High reflection band	890 nm		950 nm
Absorbance A	24 %	30 %	36 %
Modulation depth $\Delta R$	10 %	15 %	-
Non-saturable loss $A_{ns}$	-	15 %	18 %
Saturation fluence $\Phi_{sat}$	15 $\mu\text{J}/\text{cm}^2$	30 $\mu\text{J}/\text{cm}^2$	50 $\mu\text{J}/\text{cm}^2$
Relaxation time constant $\tau$	0.3 ps	0.5 ps	0.8 ps
Damage threshold $\Phi$		800 $\mu\text{J}/\text{cm}^2$	
Absorber Peak Temperature			150°C <sup>1</sup>
Chip thickness	425 $\mu\text{m}$	450 $\mu\text{m}$	475 $\mu\text{m}$
Protection	SAM is protected with a dielectric front layer		

<sup>1</sup> Please make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

**Low intensity spectral reflectance**


Mounting Options SAM-920-30-0.5ps-30-x	Description
<b>x = 4.0-0</b>	Single chip, unmounted, chip size 4.0mm x 4.0mm
<b>x = 1.0b-0</b>	Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm
<b>x = 1.3b-0</b>	Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm
<b>x = 4.0-12.7g-c / 4.0-12.7g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm Ø
<b>x = 4.0-25.0g-c / 4.0-25.0g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm Ø
<b>x = 4.0-25.4g-c / 4.0-25.4g-e</b>	chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm Ø
<b>x = 4.0-12.7s-c / 4.0-12.7s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm Ø
<b>x = 4.0-25.0s-c / 4.0-25.0s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm Ø
<b>x = 4.0-25.4s-c / 4.0-25.4s-e</b>	chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm Ø
<b>x = 4.0-25.0w-c / 4.0-25.0w-e</b>	chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter
<b>x = 4.0-25.4h-c / 4.0-25.4h-e</b>	chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application
<b>-c</b> Center mounting 	<b>-e</b> Edge mounting 
<b>x = FC/PC / FC/APC</b>	mounted on a 1 m monomode fiber cable with FC/PC / FC/APC connector  available fiber types:  780-HP, HI 980, PM780-HP, Fujikura SM85-PS-U25A (polarisation maintaining (PM) fiber)
Other chip dimensions are also possible, please ask.	